

Bill of Materials

TI DESIGNS

TIDA-00863

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Package Reference
1	1	IPC1		Printed Circuit Board	Any	TPS7B4253	
2	1	C1	22uF	CAP, AL, 22 μ F, 50 V, +/- 20%, 0.88	Panasonic	EEE-FK1H220P	SMT Radial D
3	7	C2, C3, C4, C5, C6, C7, C12	0.1uF	CAP, CERM, 0.1 μ F, 50 V, +/- 10%, X7R, 0603	MuRata	GCM188R71H104KA57D	0603
4	4	C8, C9, C10, C11	10uF	CAP, CERM, 10 μ F, 16 V, +/- 10%, X7R, AEC-Q200 Grade 1, 1206_190	MuRata	GCM31CR71C106KA64L	1206_190
5	1	D1	60V	Diode, Schottky, 60 V, 2 A, SMA	Diodes Inc.	B260A-13-F	SMA
6	3	FID1, FID2, FID3		Fiducial mark. There is nothing to	N/A	N/A	Fiducial
7	2	J1, J2		Terminal Block, 6A, 3.5mm Pitch,	On-Shore Technology	ED555/2DS	7.0x8.2x6.5mm
8	6	R1, R2, R3, R4, R5, R6	10.0k	RES, 10.0 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060310K0FKEA	0603
9	3	R7, R8, R9	0.2	RES, 0.2, 1%, 1 W, 2512	Vishay-Dale	WSL2512R2000FEA	2512
10	1	R10	365	RES, 365, 1%, 0.125 W, 0805	Vishay-Dale	CRCW0805365RFKEA	0805
11	1	U1		450-mA High-Voltage Ultra-Low	Texas Instruments	TPS7B6750QPWPRQ1	PWP0020D
12	2	U2, U3		300mA Low Dropout Voltage	Texas Instruments	TPS7B4253QPWPRQ1	PWP0020D

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